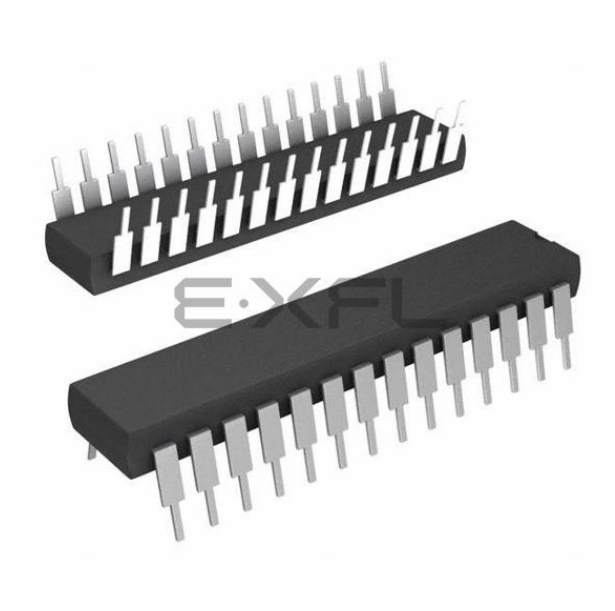

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	24
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1718-i-sp

TABLE 1-3: PIC16(L)F1717/9 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C1IN0-/C2IN0-/ CLCIN0(1)	RA0	TTL/ST	CMOS	General purpose I/O.
	AN0	AN	—	ADC Channel 0 input.
	C1IN0-	AN	—	Comparator C2 negative input.
	C2IN0-	AN	—	Comparator C3 negative input.
	CLCIN0	TTL/ST	—	Configurable Logic Cell source input.
RA1/AN1/C1IN1-/C2IN1-/ OPA1OUT/CLCIN1(1)	RA1	TTL/ST	CMOS	General purpose I/O.
	AN1	AN	—	ADC Channel 1 input.
	C1IN1-	AN	—	Comparator C1 negative input.
	C2IN1-	AN	—	Comparator C2 negative input.
	OPA1OUT	—	AN	Operational Amplifier 1 output.
	CLCIN1	TTL/ST	—	Configurable Logic Cell source input.
RA2/AN2/VREF-/C1IN0+/C2IN0+/ DAC1OUT1	RA2	TTL/ST	CMOS	General purpose I/O.
	AN2	AN	—	ADC Channel 2 input.
	VREF-	AN	—	ADC Negative Voltage Reference input.
	C1IN0+	AN	—	Comparator C2 positive input.
	C2IN0+	AN	—	Comparator C3 positive input.
	DAC1OUT1	—	AN	Digital-to-Analog Converter output.
RA3/AN3/VREF+/C1IN1+	RA3	TTL/ST	CMOS	General purpose I/O.
	AN3	AN	—	ADC Channel 3 input.
	VREF+	AN	—	ADC Voltage Reference input.
	C1IN1+	AN	—	Comparator C1 positive input.
RA4/OPA1IN+/T0CKI(1)	RA4	TTL/ST	CMOS	General purpose I/O.
	OPA1IN+	AN	—	Operational Amplifier 1 non-inverting input.
	T0CKI	TTL/ST	—	Timer0 gate input.
RA5/AN4/OPA1IN-/DAC2OUT1/ $\overline{SS}$(1)	RA5	TTL/ST	CMOS	General purpose I/O.
	AN4	AN	—	ADC Channel 4 input.
	OPA1IN-	AN	—	Operational Amplifier 1 inverting input.
	DAC2OUT1	—	AN	Digital-to-Analog Converter output.
	$\overline{SS}$	—	—	Slave Select enable input.
RA6/OSC2/CLKOUT	RA6	TTL/ST	CMOS	General purpose I/O.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	FOSC/4 output.
RA7/OSC1/CLKIN	RA7	TTL/ST	CMOS	General purpose I/O.
	OSC1	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKIN	ST	—	External clock input (EC mode).
RB0/AN12/C2IN1+/ZCD/ COGIN(1)	RB0	TTL/ST	CMOS	General purpose I/O.
	AN12	AN	—	ADC Channel 12 input.
	C2IN1+	AN	—	Comparator C2 positive input.
	ZCD	AN	—	Zero-Cross Detection Current Source/Sink.
	COGIN	TTL/ST	—	Complementary Output Generator input.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open-Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

Note 1: Default peripheral input. Alternate pins can be selected as the peripheral input with the PPS input selection registers.

2: All pin digital outputs default to PORT latch data. Alternate outputs can be selected as the peripheral digital output with the PPS output selection registers.

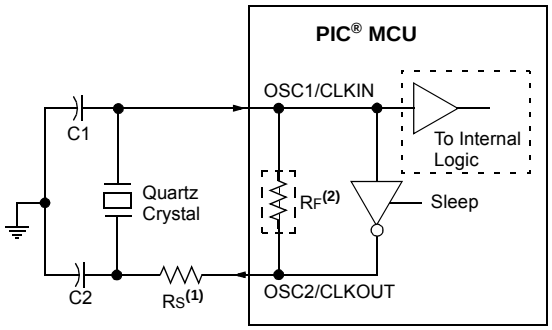
3: These peripheral functions are bidirectional. The output pin selections must be the same as the input pin selections.

TABLE 3-10: PIC16(L)F1717/8/9 MEMORY MAP, BANK 31

Bank 31	
F8Ch	
FE3h	
FE4h	STATUS_SHAD
FE5h	WREG_SHAD
FE6h	BSR_SHAD
FE7h	PCLATH_SHAD
FE8h	FSR0L_SHAD
FE9h	FSR0H_SHAD
FEAh	FSR1L_SHAD
FEBh	FSR1H_SHAD
FECh	—
FEDh	STKPTR
FEEh	TOSL
FEFh	TOSH
FF0h	—
FFFh	

Legend: = Unimplemented data memory locations, read as '0',

FIGURE 6-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

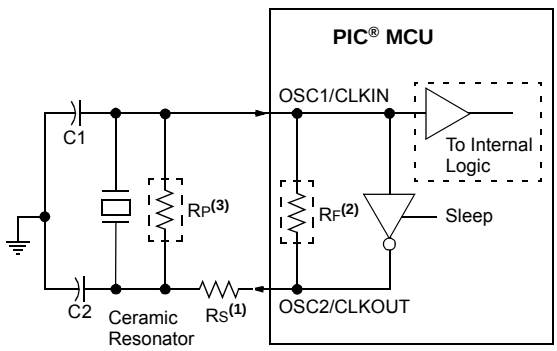
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 6-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

6.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended, unless either FSCM or Two-Speed Start-Up are enabled. In this case, code will continue to execute at the selected INTOSC frequency while the OST is counting. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 6.4 "Two-Speed Clock Start-up Mode"**).

REGISTER 11-5: WPUA: WEAK PULL-UP PORTA REGISTER(1,2)

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
WPUA7	WPUA6	WPUA5	WPUA4	WPUA3	WPUA2	WPUA1	WPUA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **WPUA<7:0>**: Weak Pull-up Register bits
1 = Pull-up enabled
0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is configured as an output.

REGISTER 11-6: ODCONA: PORTA OPEN-DRAIN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ODA7	ODA6	ODA5	ODA4	ODA3	ODA2	ODA1	ODA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ODA<7:0>:** PORTA Open-Drain Enable bits
For RA<7:0> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

11.5 PORTC Registers

11.5.1 DATA REGISTER

PORTC is an 8-bit wide bidirectional port. The corresponding data direction register is TRISC (Register 11-18). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTC register (Register 11-17) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATC).

11.5.2 DIRECTION CONTROL

The TRISC register (Register 11-18) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

11.5.3 INPUT THRESHOLD CONTROL

The INLVLC register (Register 11-24) controls the input voltage threshold for each of the available PORTC input pins. A selection between the Schmitt Trigger CMOS or the TTL compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTC register and also the level at which an interrupt-on-change occurs, if that feature is enabled. See Table 34-4: I/O Ports for more information on threshold levels.

Note:	Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin.

11.5.4 OPEN-DRAIN CONTROL

The ODCONC register (Register 11-22) controls the open-drain feature of the port. Open-drain operation is independently selected for each pin. When an ODCONC bit is set, the corresponding port output becomes an open-drain driver capable of sinking current only. When an ODCONC bit is cleared, the corresponding port output pin is the standard push-pull drive capable of sourcing and sinking current.

11.5.5 SLEW RATE CONTROL

The SLRCONC register (Register 11-23) controls the slew rate option for each port pin. Slew rate control is independently selectable for each port pin. When an SLRCONC bit is set, the corresponding port pin drive is slew rate limited. When an SLRCONC bit is cleared, The corresponding port pin drive slews at the maximum rate possible.

11.5.6 ANALOG CONTROL

The ANSELC register (Register 11-20) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELC bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELC bits has no effect on digital output functions. A pin with TRIS clear and ANSELC set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELC bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software.

11.5.7 PORTC FUNCTIONS AND OUTPUT PRIORITIES

Each pin defaults to the PORT latch data after Reset. Other functions are selected with the peripheral pin select logic. See **Section 12.0 "Peripheral Pin Select (PPS) Module"** for more information.

Analog input functions, such as ADC and comparator inputs, are not shown in the peripheral pin select lists. These inputs are active when the I/O pin is set for Analog mode using the ANSELC register. Digital output functions may continue to control the pin when it is in Analog mode.

TABLE 11-5: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELC	ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—	136
INLVLC	INLVLC7	INLVLC6	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0	137
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	135
ODCONC	ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0	137
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	135
SLRCONC	SLRC7	SLRC6	SLRC5	SLRC4	SLRC3	SLRC2	SLRC1	SLRC0	137
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	135
WPUC	WPUC7	WPUC6	WPUC5	WPUC4	WPUC3	WPUC2	WPUC1	WPUC0	136

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: VOUT RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

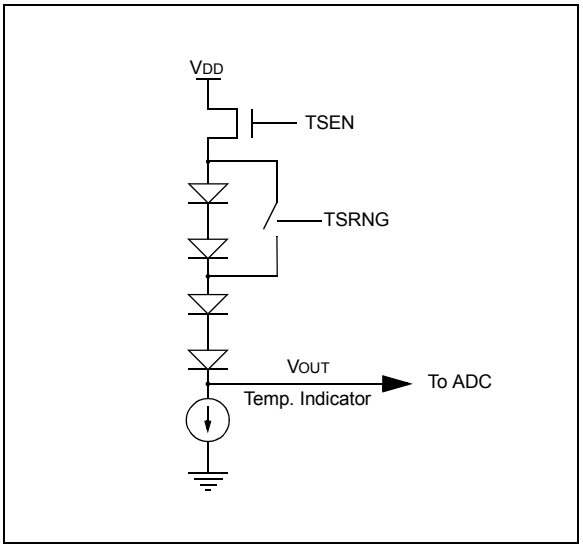
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register. When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating VDD

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum VDD vs. range setting.

TABLE 15-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 21.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

REGISTER 18-4: COGxRSIM: COG RISING EVENT SOURCE INPUT MODE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
GxRSIM7	GxRSIM6	GxRSIM5	GxRSIM4	GxRSIM3	GxRSIM2	GxRSIM1	GxRSIM0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **GxRSIM7:** COGx Rising Event Input Source 7 Mode bit
GxRIS7 = 1:
1 = NCO1_out low-to-high transition will cause a rising event after rising event phase delay
0 = NCO1_out high level will cause an immediate rising event
GxRIS7 = 0:
NCO1_out has no effect on rising event

bit 6 **GxRSIM6:** COGx Rising Event Input Source 6 Mode bit
GxRIS6 = 1:
1 = PWM3 output low-to-high transition will cause a rising event after rising event phase delay
0 = PWM3 output high level will cause an immediate rising event
GxRIS6 = 0:
PWM3 output has no effect on rising event

bit 5 **GxRSIM5:** COGx Rising Event Input Source 5 Mode bit
GxRIS5 = 1:
1 = CCP2 output low-to-high transition will cause a rising event after rising event phase delay
0 = CCP2 output high level will cause an immediate rising event
GxRIS5 = 0:
CCP2 output has no effect on rising event

bit 4 **GxRSIM4:** COGx Rising Event Input Source 4 Mode bit
GxRIS4 = 1:
1 = CCP1 low-to-high transition will cause a rising event after rising event phase delay
0 = CCP1 high level will cause an immediate rising event
GxRIS4 = 0:
CCP1 has no effect on rising event

bit 3 **GxRSIM3:** COGx Rising Event Input Source 3 Mode bit
GxRIS3 = 1:
1 = CLC1 output low-to-high transition will cause a rising event after rising event phase delay
0 = CLC1 output high level will cause an immediate rising event
GxRIS3 = 0:
CLC1 output has no effect on rising event

bit 2 **GxRSIM2:** COGx Rising Event Input Source 2 Mode bit
GxRIS2 = 1:
1 = Comparator 2 low-to-high transition will cause a rising event after rising event phase delay
0 = Comparator 2 high level will cause an immediate rising event
GxRIS2 = 0:
Comparator 2 has no effect on rising event

bit 1 **GxRSIM1:** COGx Rising Event Input Source 1 Mode bit
GxRIS1 = 1:
1 = Comparator 1 low-to-high transition will cause a rising event after rising event phase delay
0 = Comparator 1 high level will cause an immediate rising event
GxRIS1 = 0:
Comparator 1 has no effect on rising event

30.5.3.2 7-Bit Transmission

A master device can transmit a read request to a slave, and then clock data out of the slave. The list below outlines what software for a slave will need to do to accomplish a standard transmission. Figure 30-18 can be used as a reference to this list.

1. Master sends a Start condition on SDA and SCL.
2. S bit of SSP1STAT is set; SSP1IF is set if interrupt on Start detect is enabled.
3. Matching address with R/$\overline{W}$ bit set is received by the Slave setting SSP1IF bit.
4. Slave hardware generates an $\overline{ACK}$ and sets SSP1IF.
5. SSP1IF bit is cleared by user.
6. Software reads the received address from SSP1BUF, clearing BF.
7. R/$\overline{W}$ is set so CKP was automatically cleared after the $\overline{ACK}$.
8. The slave software loads the transmit data into SSP1BUF.
9. CKP bit is set releasing SCL, allowing the master to clock the data out of the slave.
10. SSP1IF is set after the $\overline{ACK}$ response from the master is loaded into the ACKSTAT register.
11. SSP1IF bit is cleared.
12. The slave software checks the ACKSTAT bit to see if the master wants to clock out more data.

Note 1: If the master $\overline{ACK}$s the clock will be stretched.

2: ACKSTAT is the only bit updated on the rising edge of SCL (9th) rather than the falling.

13. Steps 9-13 are repeated for each transmitted byte.
14. If the master sends a not $\overline{ACK}$; the clock is not held, but SSP1IF is still set.
15. The master sends a Restart condition or a Stop.
16. The slave is no longer addressed.

FIGURE 30-34: BUS COLLISION DURING START CONDITION (SCL = 0)

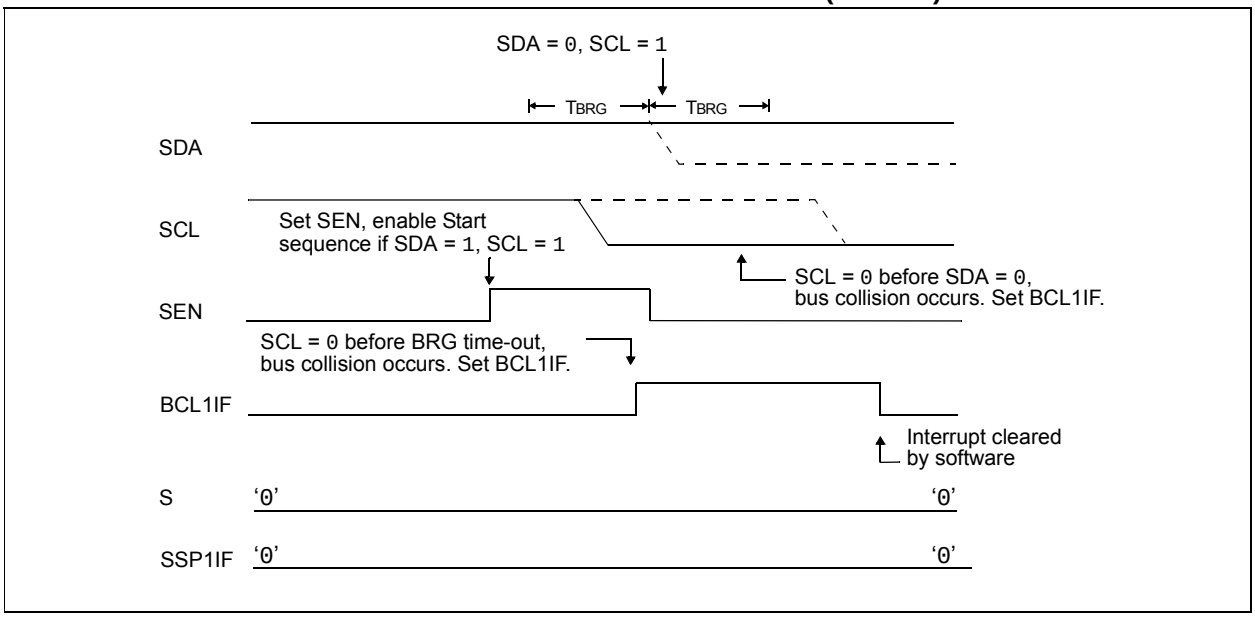
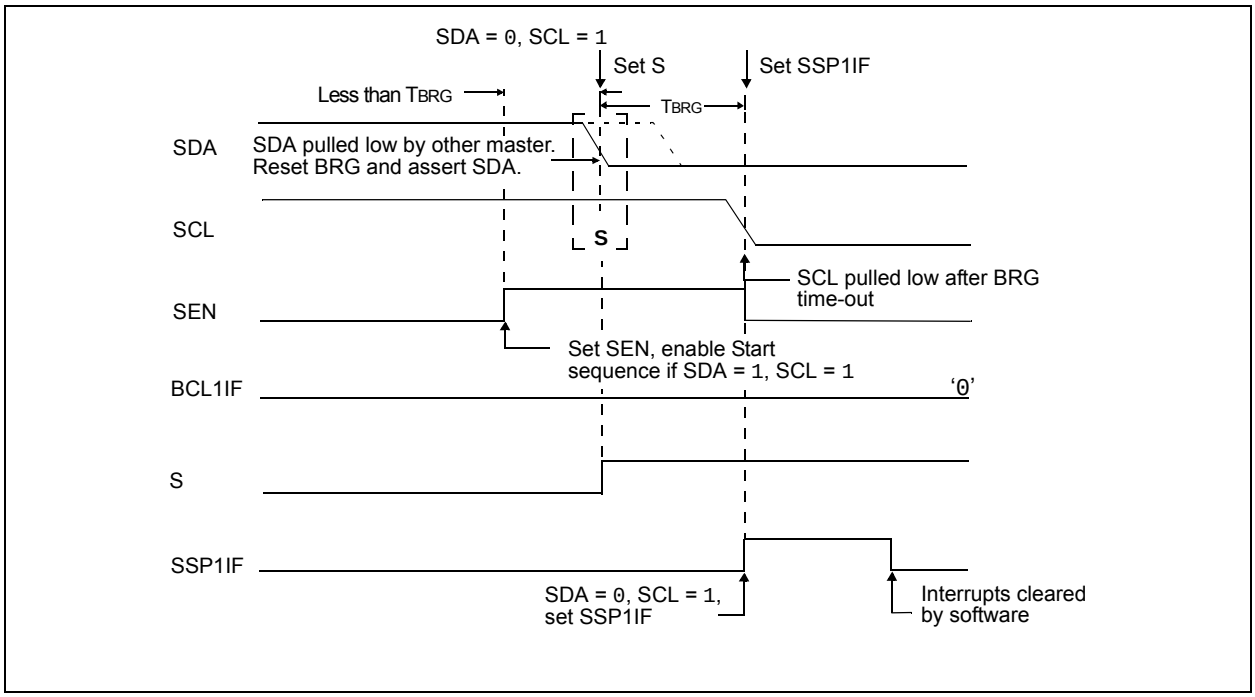


FIGURE 30-35: BRG RESET DUE TO SDA ARBITRATION DURING START CONDITION



31.4 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUD1CON register selects 16-bit mode.

The SP1BRGH, SP1BRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TX1STA register and the BRG16 bit of the BAUD1CON register. In Synchronous mode, the BRGH bit is ignored.

Table 31-3 contains the formulas for determining the baud rate. Example 31-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various Asynchronous modes have been computed for your convenience and are shown in Table 31-5. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SP1BRGH, SP1BRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is idle before changing the system clock.

EXAMPLE 31-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate = \frac{FOSC}{64([SPBRGH:SPBRGL] + 1)}$$

Solving for SP1BRGH:SP1BRGL:

$$X = \frac{\frac{FOSC}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$Calculated\ Baud\ Rate = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

31.5.1.5 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver is automatically disabled when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RC1STA register) or the Continuous Receive Enable bit (CREN of the RC1STA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RC1REG. The RCIF bit remains set as long as there are unread characters in the receive FIFO.

Note:	If the RX/DT function is on an analog pin, the corresponding ANSEL bit must be cleared for the receiver to function.

31.5.1.6 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver is automatically disabled when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

Note:	If the device is configured as a slave and the TX/CK function is on an analog pin, the corresponding ANSEL bit must be cleared.

31.5.1.7 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RC1REG is read to access the FIFO. When this happens the OERR bit of the RC1STA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RC1REG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RC1STA register or by clearing the SPEN bit which resets the EUSART.

31.5.1.8 Receiving 9-Bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RC1STA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RC1STA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RC1REG.

31.5.1.9 Synchronous Master Reception Setup

1. Initialize the SP1BRGH, SP1BRGL register pair for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
4. Ensure bits CREN and SREN are clear.
5. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
6. If 9-bit reception is desired, set bit RX9.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF will be set when reception of a character is complete. An interrupt will be generated if the enable bit RCIE was set.
9. Read the RC1STA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RC1REG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RC1STA register or by clearing the SPEN bit which resets the EUSART.

TABLE 33-3: PIC16(L)F1717/8/9 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C, DC, Z	**2**
ADDWFC	f, d	Add with Carry W and f	1	11	1101	dfff	ffff	C, DC, Z	**2**
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	**2**
ASRF	f, d	Arithmetic Right Shift	1	11	0111	dfff	ffff	C, Z	**2**
LSLF	f, d	Logical Left Shift	1	11	0101	dfff	ffff	C, Z	**2**
LSRF	f, d	Logical Right Shift	1	11	0110	dfff	ffff	C, Z	**2**
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	**2**
CLRW	–	Clear W	1	00	0001	0000	00xx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	**2**
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	**2**
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	**2**
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	**2**
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	**2**
MOVWF	f	Move W to f	1	00	0000	1fff	ffff		**2**
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	**2**
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	**2**
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C, DC, Z	**2**
SUBWFB	f, d	Subtract with Borrow W from f	1	11	1011	dfff	ffff	C, DC, Z	**2**
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		**2**
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	**2**
BYTE ORIENTED SKIP OPERATIONS									
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		**1, 2**
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		**1, 2**
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		**2**
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		**2**
BIT-ORIENTED SKIP OPERATIONS									
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		**1, 2**
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		**1, 2**
LITERAL OPERATIONS									
ADDLW	k	Add literal and W	1	11	1110	kkkk	kkkk	C, DC, Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLB	k	Move literal to BSR	1	00	0000	001k	kkkk		
MOVLP	k	Move literal to PCLATH	1	11	0001	1kkk	kkkk		
MOVLW	k	Move literal to W	1	11	0000	kkkk	kkkk		
SUBLW	k	Subtract W from literal	1	11	1100	kkkk	kkkk	C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	
CONTROL OPERATIONS									
BRA	k	Relative Branch	2	11	001k	kkkk	kkkk		
BRW	–	Relative Branch with W	2	00	0000	0000	1011		
CALL	k	Call Subroutine	2	10	0kkk	kkkk	kkkk		
CALLW	–	Call Subroutine with W	2	00	0000	0000	1010		
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
RETFIE	k	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	0100	kkkk	kkkk		
RETURN	–	Return from Subroutine	2	00	0000	0000	1000		

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

33.2 Instruction Descriptions

ADDFSR — Add Literal to FSRn

Syntax:	[*label*] ADDFSR FSRn, k
Operands:	-32 ≤ k ≤ 31 n ∈ [0, 1]
Operation:	FSR(n) + k → FSR(n)
Status Affected:	None
Description:	The signed 6-bit literal 'k' is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h-FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

ADDLW — Add literal and W

Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.

ADDWF — Add W and f

Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ADDWFC — ADD W and CARRY bit to f

Syntax:	[*label*] ADDWFC f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) + (C) → dest
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'.

ANDLW — AND literal with W

Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

ANDWF — AND W with f

Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ASRF — Arithmetic Right Shift

Syntax:	[*label*] ASRF f {,d}
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f<7>)→ dest<7> (f<7:1>) → dest<6:0>, (f<0>) → C,
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

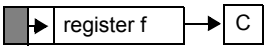


TABLE 34-9: PLL CLOCK TIMING SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.†**	**Max.**	**Units**	**Conditions**
F10	FOSC	Oscillator Frequency Range	4	—	8	MHz	
F11	FSYS	On-Chip VCO System Frequency	16	—	32	MHz	
F12	TRC	PLL Start-up Time (Lock Time)	—	—	2	ms	
F13*	ΔCLK	CLKOUT Stability (Jitter)	-0.25%	—	+0.25%	%	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

:

TABLE 34-15: ANALOG-TO-DIGITAL CONVERTER (ADC) CHARACTERISTICS(1,2,3,4)

Standard Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C, Single-ended, 2 μs TAD, VREF+ = 3V, VREF- = VSS							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10	bit	
AD02	EIL	Integral Error	—	—	±1.7	LSb	VREF = 3.0V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes, VREF = 3.0V
AD04	EOFF	Offset Error	—	—	±2.5	LSb	VREF = 3.0V
AD05	EGN	Gain Error	—	—	±2.0	LSb	VREF = 3.0V
AD06	VREF	Reference Voltage	1.8	—	VDD	V	VREF = (VREF+ minus VREF-)
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	Can go higher if external 0.01μF capacitor is present on input pin.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The ADC conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF+ pin, VDD pin or FVR, whichever is selected as reference input.

4: See **Section 35.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

TABLE 34-16: ADC CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	ADC Clock Period (TADC)	1.0	—	9.0	μs	FOSC-based
		ADC Internal FRC Oscillator Period (TFRC)	1.0	2	6.0	μs	ADCS<1:0> = 11 (ADC FRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	5.0	—	μs	
AD133*	THCD	Holding Capacitor Disconnect Time	—	1/2 TAD	—		ADCS<2:0> ≠ x11 (FOSC-based)
			—	1/2 TAD + 1TCY	—		ADCS<2:0> = x11 (FRC-based)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The ADRES register may be read on the following TCY cycle.

Note: Unless otherwise noted, VIN = 5V, FOSC = 500 kHz, CIN = 0.1 µF, TA = 25°C.

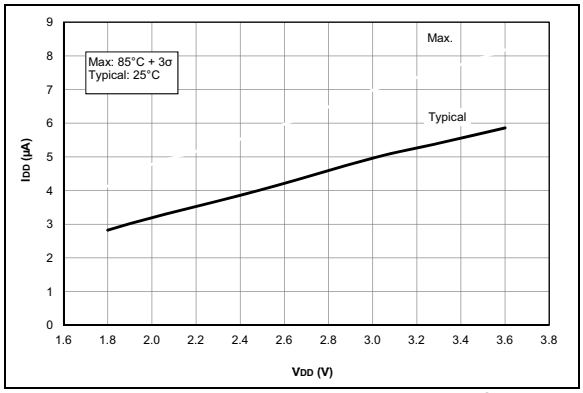


FIGURE 35-19: *IDD, LFINTOSC Mode, Fosc = 31 kHz, PIC16LF1717/8/9 Only.*

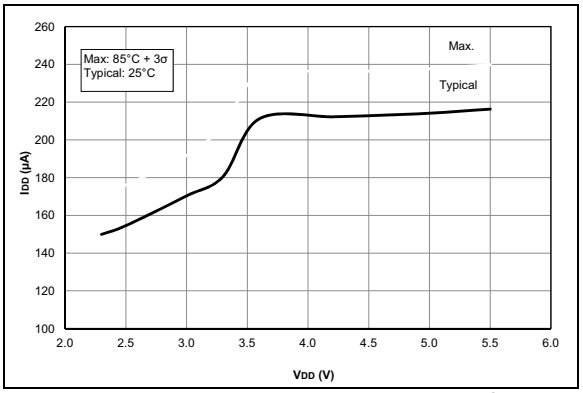


FIGURE 35-22: *IDD, MFINTOSC Mode, Fosc = 500 kHz, PIC16F1717/8/9 Only.*

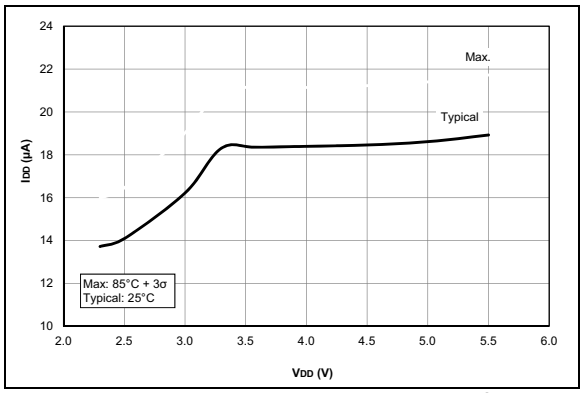


FIGURE 35-20: *IDD, LFINTOSC Mode, Fosc = 31 kHz, PIC16F1717/8/9 Only.*

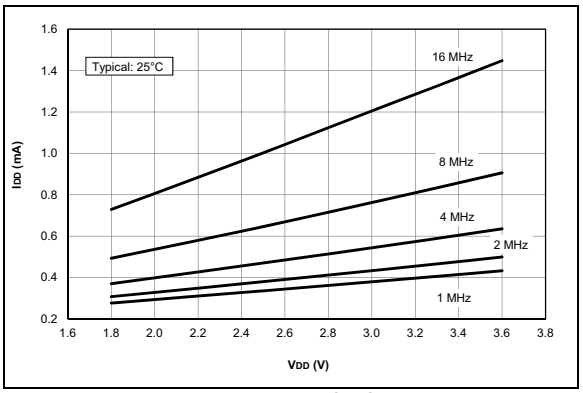


FIGURE 35-23: *IDD Typical, HFINTOSC Mode, PIC16LF1717/8/9 Only.*

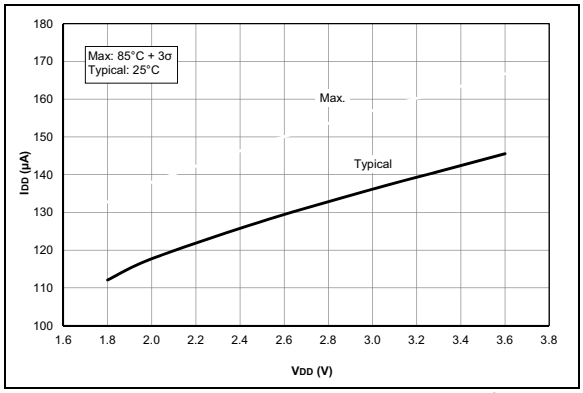


FIGURE 35-21: *IDD, MFINTOSC Mode, Fosc = 500 kHz, PIC16LF1717/8/9 Only.*

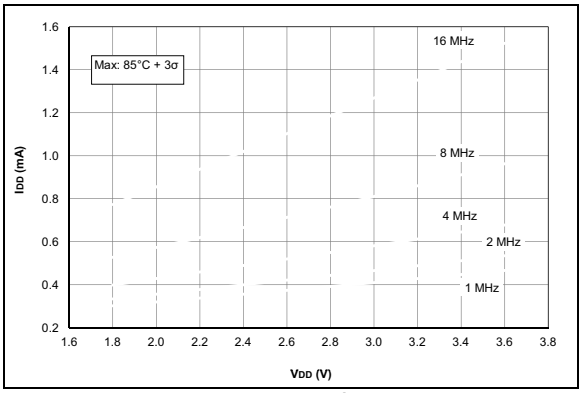


FIGURE 35-24: *IDD Maximum, HFINTOSC Mode, PIC16LF1717/8/9 Only.*

Note: Unless otherwise noted, V_{IN} = 5V, F_{OSC} = 500 kHz, C_{IN} = 0.1 µF, T_A = 25°C.

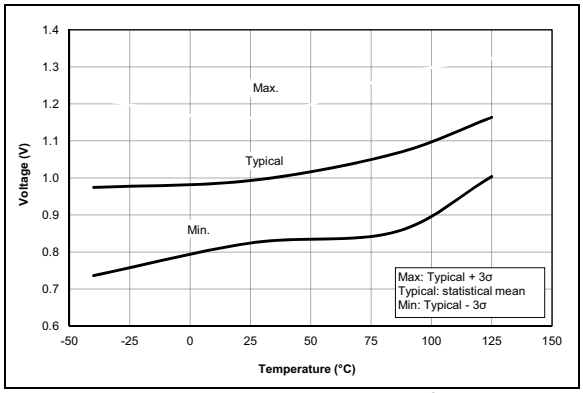


FIGURE 35-73: *POR Rearm Voltage, NP Mode, PIC16LF1717/8/9 Only.*

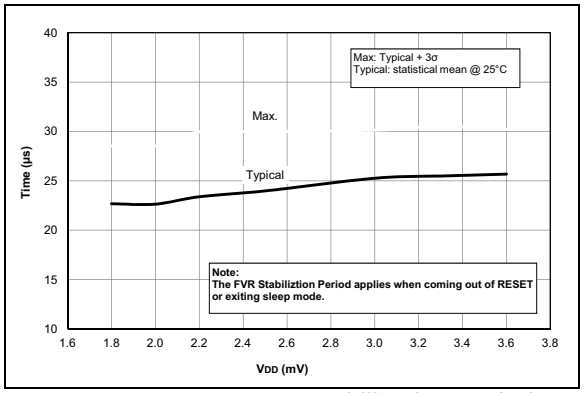


FIGURE 35-76: *FVR Stabilization Period, PIC16LF1717/8/9 Only.*

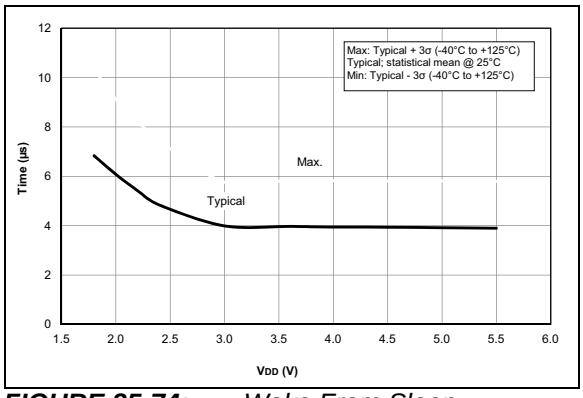


FIGURE 35-74: *Wake From Sleep, VREGPM = 0.*

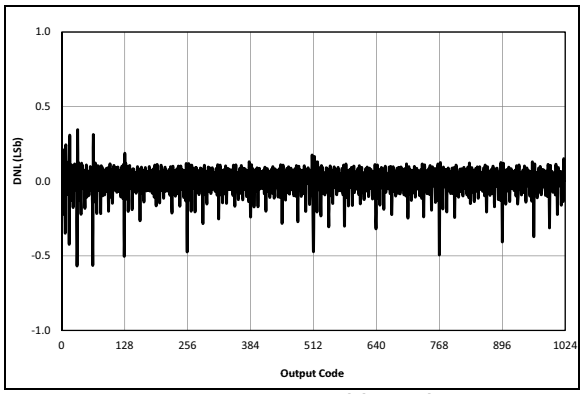


FIGURE 35-77: *ADC 10-bit Mode, Single-Ended DNL, V_{DD} = 3.0V, T_{AD} = 1 µS, 25°C.*

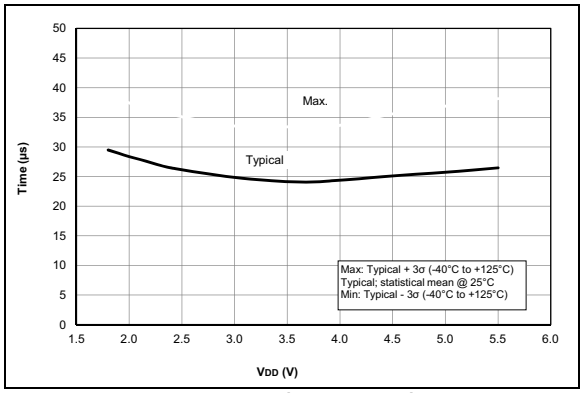


FIGURE 35-75: *Wake From Sleep, VREGPM = 1.*

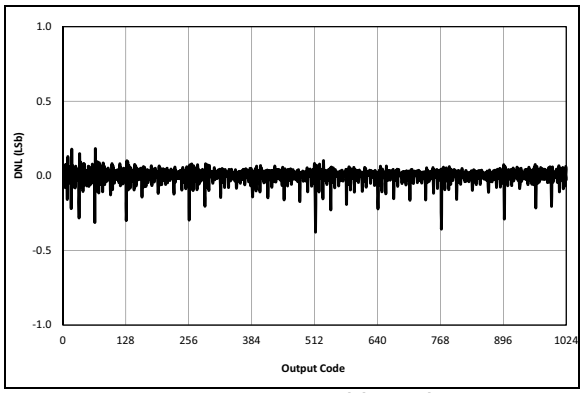
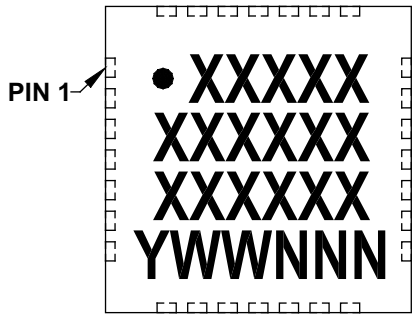


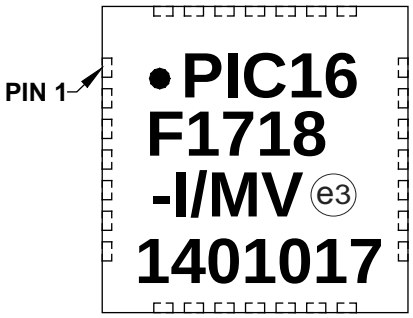
FIGURE 35-78: *ADC 10-bit Mode, Single-Ended DNL, V_{DD} = 3.0V, T_{AD} = 4 µS, 25°C.*

Package Marking Information (Continued)

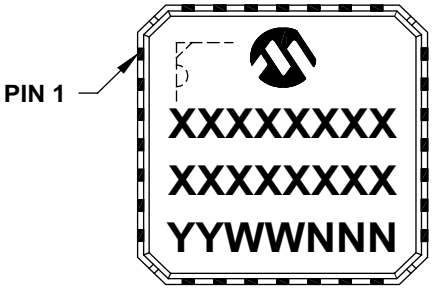
28-Lead UQFN (4x4x0.5 mm)



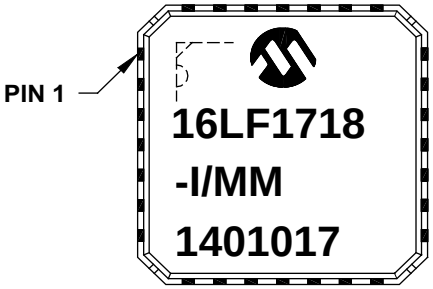
Example



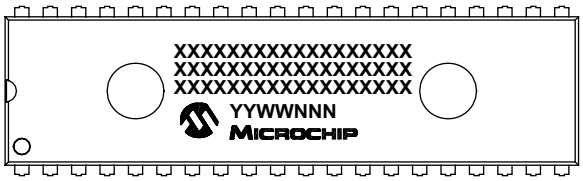
28-Lead QFN (6x6x0.9 mm)



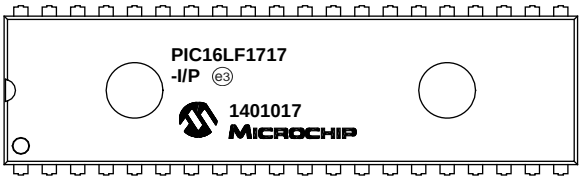
Example



40-Lead PDIP (600 mil)



Example

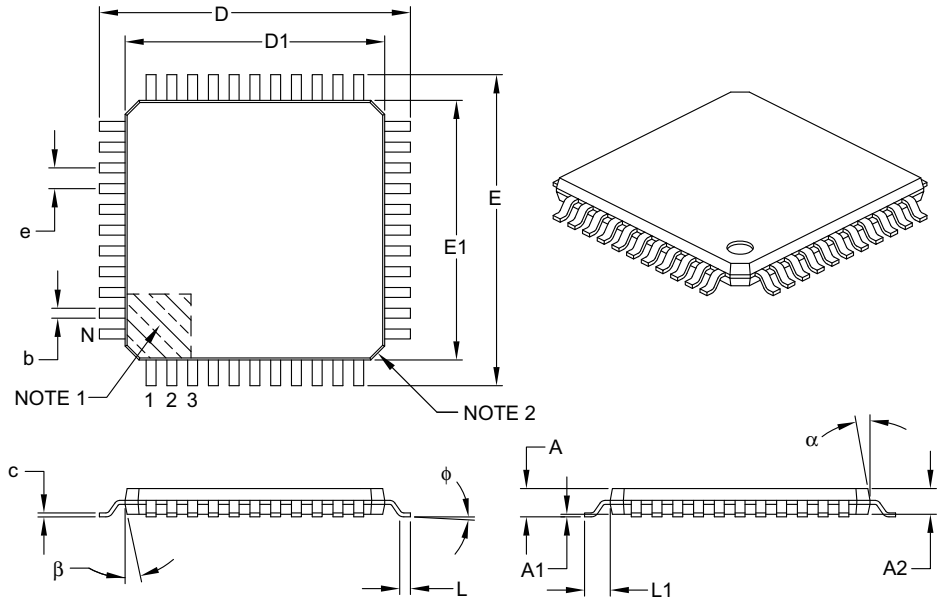


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B